

Title (en)
COPPER-ZINC ALLOY ELECTROPLATING BATH AND PLATING METHOD USING THE COPPER-ZINC ALLOY ELECTROPLATING BATH

Title (de)
GALVANISIERUNGSBAD AUS KUPFER-ZINK-LEGIERUNG UND PLATTIERUNGSVERFAHREN MIT DEM GALVANISIERUNGSBAD AUS KUPFER-ZINK-LEGIERUNG

Title (fr)
BAIN D'ÉLECTRODÉPOSITION D'ALLIAGE CUIVRE-ZINC ET PROCÉDÉ DE DÉPOSITION UTILISANT LE BAIN D'ÉLECTRODÉPOSITION D'ALLIAGE CUIVRE-ZINC

Publication
EP 2218804 A4 20110824 (EN)

Application
EP 08854020 A 20081126

Priority
• JP 2008071470 W 20081126
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• JP 2007304376 A 20071126

Abstract (en)
[origin: EP2218804A1] A cyanide-free copper-zinc alloy electroplating bath is provided which can form a uniform and glossy alloy layer having the desired composition even at a higher current density than that for a conventional electroplating bath, and which is excellent in productivity. The copper-zinc alloy electroplating bath comprises at least one selected from a copper salt, zinc salt, alkali metal pyrophosphate, and amino acid or a salt thereof, and has a pH of 8.5 to 14. The pH is preferably 10.5 to 11.8; and the concentration of the amino acid or a salt thereof is preferably 0.08 mol/L to 0.22 mol/L, more preferably 0.1 mol/L to 0.13 mol/L. As the amino acid or a salt thereof, histidine or a salt thereof may be preferably used.

IPC 8 full level
C25D 3/58 (2006.01)

CPC (source: EP US)
C25D 3/58 (2013.01 - EP US); **C25D 3/38** (2013.01 - EP US)

Citation (search report)
• No further relevant documents disclosed
• See references of WO 2009069669A1

Citation (examination)
• EP 0752484 A1 19970108 - PIRELLI [IT]
• GB 1498212 A 19780118 - MCGEAN CHEM CO INC
• SENNA L F ET AL: "ELECTRODEPOSITION OF COPPER-ZINC ALLOYS IN PYROPHOSPHATE-BASED ELECTROLYTES", JOURNAL OF APPLIED ELECTROCHEMISTRY, SPRINGER, DORDRECHT, NL, vol. 33, no. 12, 1 December 2003 (2003-12-01), pages 1155 - 1161, XP001211549, ISSN: 0021-891X, DOI: 10.1023/B:JACH.00000003756.11862.6E

Cited by
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